

规格书编号

SPEC NO:

产品规格书 SPECIFICATION

CUSTOMER 客户:				
PRODUCT 产品:	SAW FILTER			
MODEL NO 型 号:	HDF429AF11			
PREPARED 编 制:	CHECKED 审 核	₹:		
APPROVED 批准:	DATE 日 期]: 2006-5-11		
客户确认 CUSTOMER RE	CEIVED:			
审核 CHECKED	批准 APPROVED	日期 DATE		

无锡市好达电子有限公司 Shoulder Electronics Limited



SAW FILTER HDF429AF11

更改历史记录 History Record

更改日期 Date	规格书编号 Spec. No.	产品型号 Part No.	客户产品型号 Customer No.	更改内容描述 Modify Content	备注 Remark



1. SCOPE

SAW FILTER

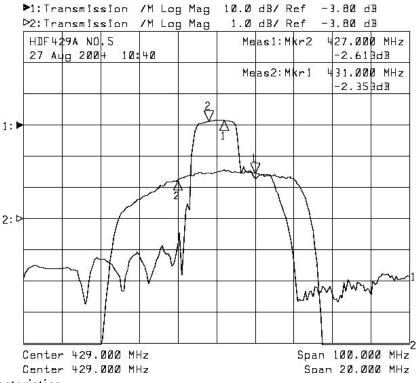
This specification shall cover the characteristics of SAW filter With 429MHz used for the page system.

2. ELECTRICAL SPECIFICATION

DC Voltage VDC	10V	
AC Voltage Vpp	10V50Hz/60Hz	
Operation temperature	-40°C to +85°C	
Storage temperature	-45°C to +85°C	
RF Power Dissipation	0dBm	

Electronic Characteristics

2-1. Typical frequency response



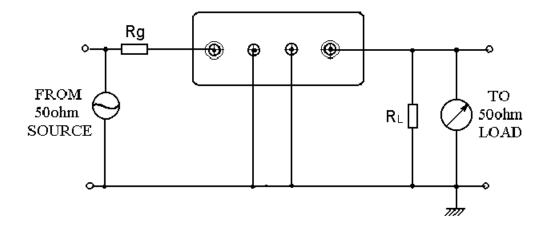
2-2. Electrical characteristics

PART NUMBER	HDF429A	UNIT
NOMINAL CENTERREQUENCY(Fo)	429.0	MHz
INSERTION LOSS:		
1. Fo-100MHz TO Fo -39.8 MHz	45.0 MIN	αL
2. Fo \pm 3 MHz	4.5 MIN	dB
3. Fo+39.8 TO Fo +100MHz	45.0 MIN	
4. RIPPLE (Fo ± 3 MHz)	2.0 MAX	dB
INPUT AND OUTPUT IMPEDANCE	50/0	Ω/pF

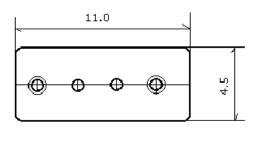


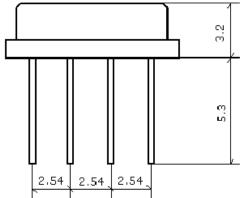
SAW FILTER HDF429AF11

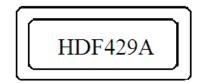
3. TEST CIRCUIT



5. DIMENSION







5. ENVIRONMENTAL CHARACTERISTICS

5-1 Temperature cycling

Subject the device to a low temperature of -40 $^\circ \! C$ for 30 minutes. Following by a high temperature of +25 $^\circ \! C$ for 5 Minutes and a higher temperature of +85 $^\circ \! C$ for 30



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Minutes. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall meet the specifications in 2-2.

5-2 Resistance to solder heat

Submerge the device terminals into the solder bath at 260° C $\pm 5^{\circ}$ C for 10 ± 1 sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in 2-2.

5-3 Solderability

Submerge the device terminals into the solder bath at 245° C $\pm 5^{\circ}$ C for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in 2-2.

5-4 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1 m 3 times. the filter shall fulfill the specifications in 2-2.

5-5 Vibration

Subject the device to the vibration for 2 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 hz. The filter shall fulfill the specifications in 2-2.

6. REMARK

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration &destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.